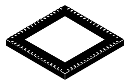
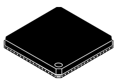


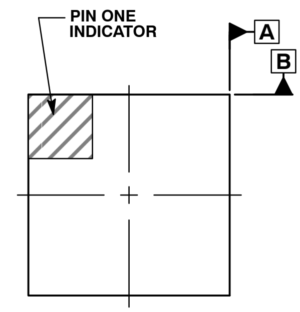
SCALE 1:1



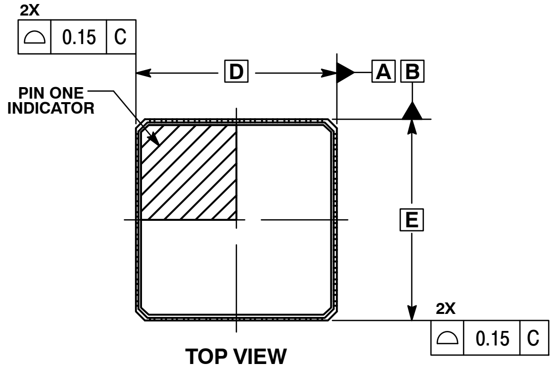
SCALE 1:1

QFN64 9x9, 0.5P (PUNCH & SAWN)
CASE 485DH
ISSUE O

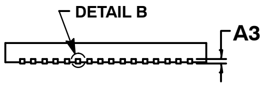
DATE 27 AUG 2013



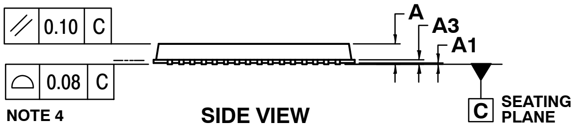
TOP VIEW
ALTERNATE CONSTRUCTION



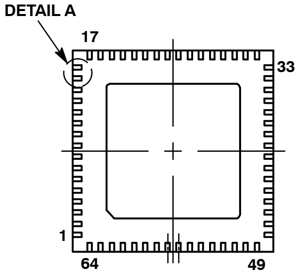
TOP VIEW



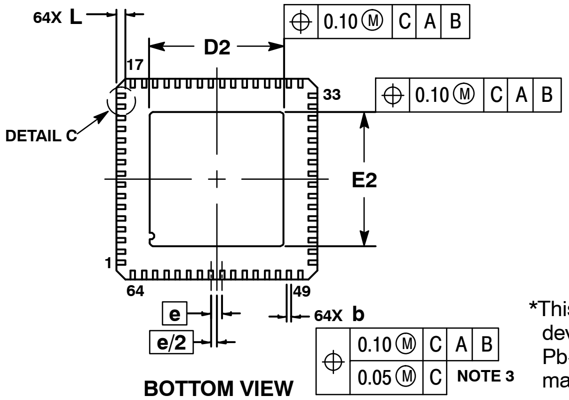
SIDE VIEW
ALTERNATE CONSTRUCTION



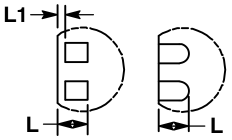
SIDE VIEW



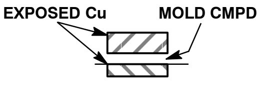
BOTTOM VIEW
ALTERNATE CONSTRUCTION



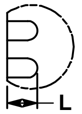
BOTTOM VIEW



DETAIL A
ALTERNATE CONSTRUCTIONS



DETAIL B
ALTERNATE CONSTRUCTION



DETAIL C
ALTERNATE CONSTRUCTION

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM THE TERMINAL TIP
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. ALL DIMENSIONS APPLY TO BOTH THE SAWN AND PUNCH PACKAGES.

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.18	0.30
D	9.00 BSC	
D2	5.90	6.25
E	9.00 BSC	
E2	5.90	6.25
e	0.50 BSC	
L	0.30	0.50
L1	0.00	0.15

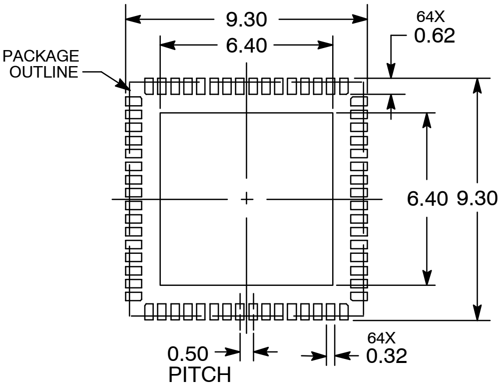
GENERIC MARKING DIAGRAM*

1 ○
XXXXXXXXX
XXXXXXXXX
AWLYYWWG

XXXXX	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**QFN64 9x9, 0.5P (PUNCH & SAWN)**	**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY I. MARIANO.	27 AUG 2013

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